



Embedded Systems Week

www.esweek.org

September 17-22, 2023
Hamburg, Germany



Call for Late-Breaking (LB) and Work-in-Progress (WIP) Papers

• CASES • CODES+ISSS • EMSOFT • MEMOCODE • NOCS • Workshops • Tutorials •

About Embedded Systems Week (ESWEEK)

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for smart, intelligent and connected computing systems. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), two symposia (MEMOCODE, NOCS), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

One Registration, three Conferences!

Registered attendees can attend sessions in any of the ESWEEK conferences (CASES, CODES+ISSS, EMSOFT). Please note that tutorials, symposia (MEMOCODE, NOCS), and workshops may use separate registration.

ESWEEK 2023 will be an in-person event, taking place in Hamburg, Germany. We will continue to monitor specific travel advisories through official channels, which include the World Health Organization (WHO) and the local Ministry of Health. Please refer to the conference web-site and social media channels for updates.

Call for LB and WIP Papers

ESWEEK'23 introduces a new track: **Late-Breaking (LB) Result papers** for its three conferences. **LB papers** provide a venue for quick dissemination of research ideas to the embedded systems community and are expected to represent complete and mature works written in a condensed form.

Work-in-Progress (WIP) papers are intended as a venue to report early or ongoing research activities representing work that has not been fully realized or developed, for which full empirical data may not yet be available, or that has not yet reached a level of maturity expected for other types of submissions.

ESWEEK invites you to submit up to 4 pages of original research articles for LB papers, and up to 2 pages for WIP papers, in an IEEE/ACM double-column, 10 pt format. Both LB and WIP papers must be submitted to either one of the three conferences and will go through 2 rounds of reviews. If accepted, the LB papers will be published in IEEE ESL (Embedded Systems Letters), while WIP papers will be published in ESWEEK proceedings of the respective conferences. The authors of accepted LB and WIP papers will present a poster of their work, and a lightning talk at ESWEEK. Authors of accepted LB papers will also need to submit a 3-minute video when submitting the final camera-ready version of the paper. When submitting an LB/WIP paper, please follow the appropriate conference submission sites.

For detailed topic areas of CASES, please visit <https://esweek.org/cases>.

For detailed topic areas of CODES+ISSS, please visit <https://esweek.org/codes+iss>.

For detailed topic areas of EMSOFT, please visit <https://esweek.org/emsoft>.

Sponsoring Societies:



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Timeline of LB/WIP Papers

LB/WIP Paper submission (firm):

May 22, 2023

First round of notification: June 2, 2023

Submit revision: June 19, 2023

Final notification: July 3, 2023

Camera-ready submission: July 13, 2023

CASES

International Conference on
Compilers, Architectures, and
Synthesis for Embedded Systems

International Conference on
Hardware/Software Codesign
and System Synthesis



EMSOFT

International Conference
on Embedded Software